

SOT1369-3

plastic thermal enhanced very thin quad flat package; no leads; 40 terminals; body 5 mm x 5 mm x 0.85 mm

1 June 2017

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN40
Package type industry code	HVQFN40
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	18-5-2016
Manufacturer package code	SOT1369

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.95	-	5	5.05	mm
E	package width	4.95	-	5	5.05	mm
A	seated height	0.8	-	0.85	0.9	mm
e	nominal pitch	-	-	0.4	-	mm

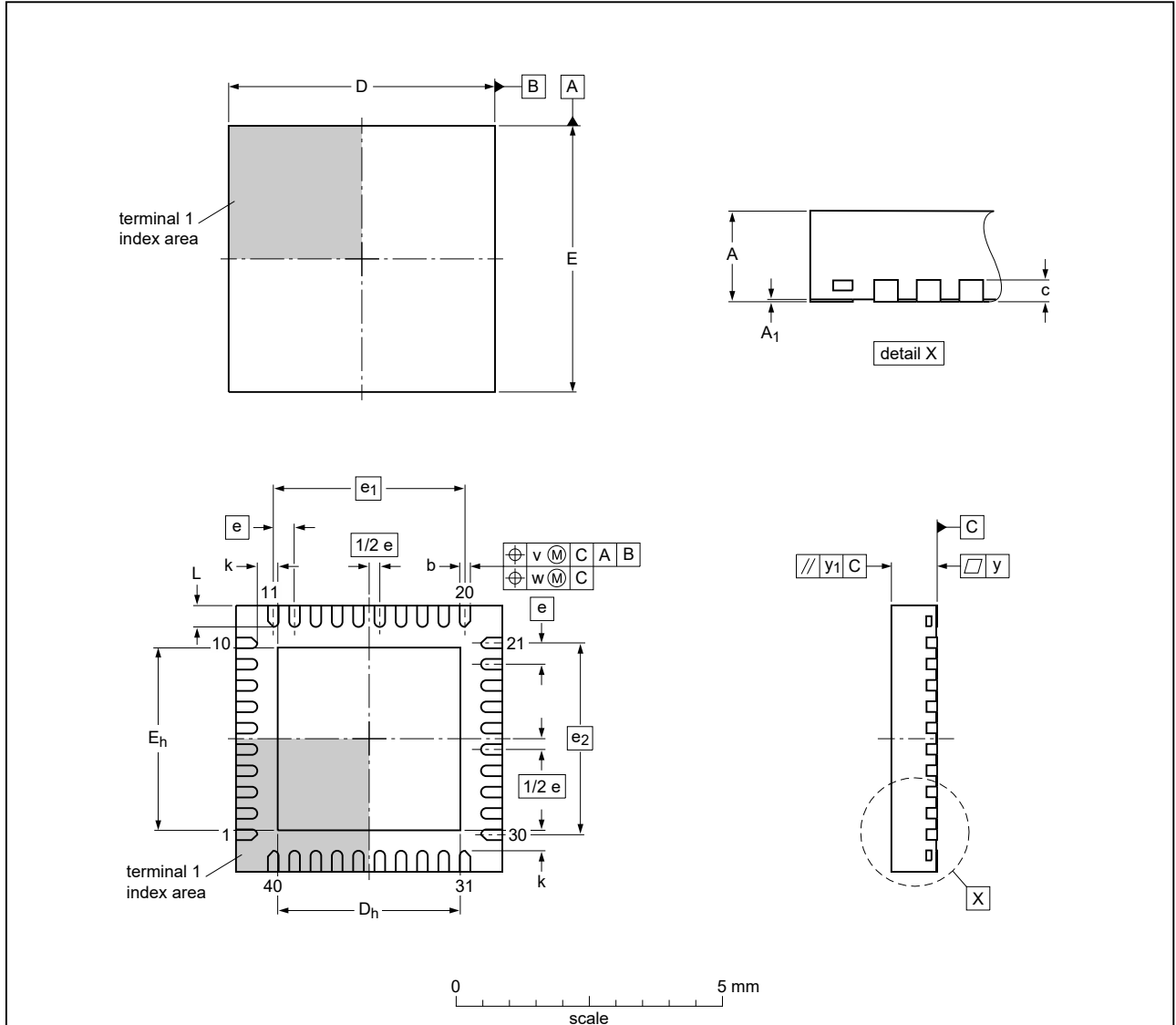


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2. Package outline

HVQFN40: plastic thermal enhanced very thin quad flat package; no leads; 40 terminals; body 5 x 5 x 0.85 mm

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Dimensions (mm are the original dimensions)

Unit	A	A ₁	b	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	e ₁	e ₂	L	k	v	w	y	y ₁
max	0.90	0.05	0.27		5.05	3.55	5.05	3.55				0.45					
nom	0.85		0.22	0.2	5.00	3.45	5.00	3.45	0.4	3.6	3.6	0.40	0.375	0.1	0.05	0.05	0.1
min	0.80	0.00	0.15		4.95	3.35	4.95	3.35				0.35					

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot1369-3_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1369-3		---			16-01-12 16-03-08

Fig. 1. Package outline HVQFN40 (SOT1369-3)

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3. Soldering

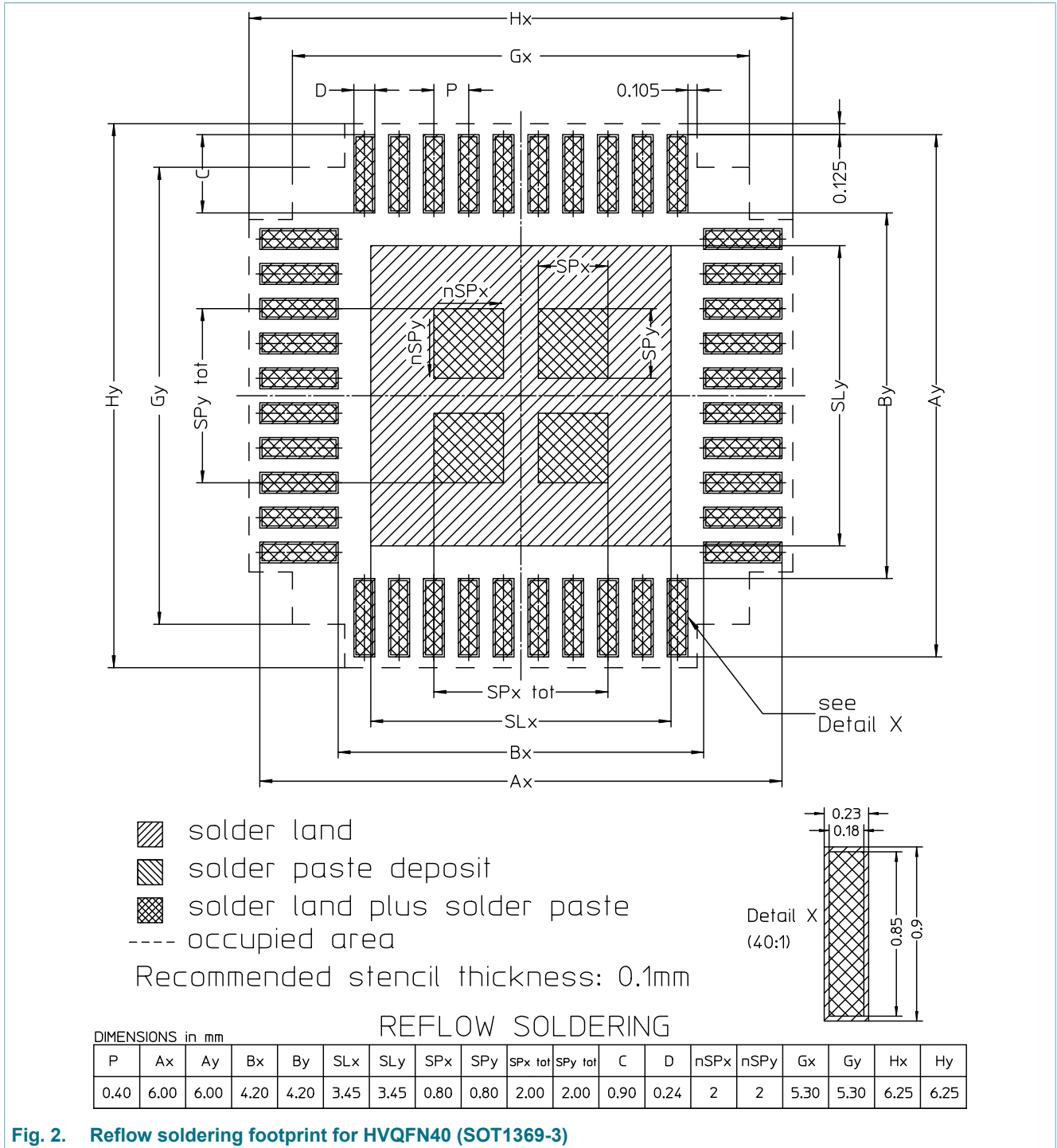


Fig. 2. Reflow soldering footprint for HVQFN40 (SOT1369-3)

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4. Legal information

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Date of release: 1 June 2017
